

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
K. Okajima, et al.

Serial No.: To Be Assigned Art Unit: To Be Assigned
Filed: Concurrently Herewith Examiner: To Be Assigned
For: Method For Forming Solder-Resist Film

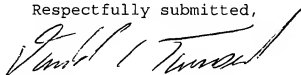
INFORMAL FILING OF NEW PATENT APPLICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
BOX PATENT APPLICATIONS

Sir:

The undersigned has been authorized by the Applicants, Keiichi OKAJIMA, Hiroshi ODA and Takahiro NAKANO to file the enclosed patent application, and to defer filing of the Declaration/Power of Attorney.

Respectfully submitted,



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Date: July 31, 2003

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